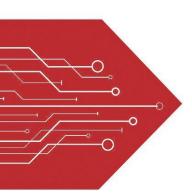
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet









Other Data

End termination

Packaging

Complies with Standard

Notes:

Body

*1 AC voltage at 50~60Hz

- *2 Varistor voltage
- *3 Capacitance
- *4 Maximum clamping voltage
- *5 Rated peak single pulse transient current

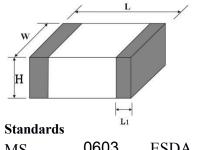
ZnO Ag/Ni/Sn Tape

IEC61000-4-2、IEC61000-4-5

Measured at 1mA DC Measured at f=1kHz,Vrms=0.5V Measured at 1A by 8/20µs Pulse Measured by 8/20µs Pulse

Unit: mm

PKG	Length (L)	Width (W)	High (H) Max	Termination (L1)
0603	1.60±0.15	0.80±0.15	0.95	0.35 ± 0.15



 $\begin{array}{ccc} \text{MS} & \underline{0603} & \underline{\text{ESDA}} & \text{XX} \\ 1 & 2 & 3 & 4 \end{array}$

①production series: msksemi

②size: 0603

③type: ESD高分子保护器件 ④ V_{DC:} 5V 9V 12V 14V 18V 24V

Technical Data	Symbol	Value	Unit
Maximum allowable continuous DC voltage	V_{DC}	5.0	V
Varistor voltage Measured*2	V _B	130	V
Varistor voltage tolerance		±20	%
Typical capacitance value measured*3	C	1.0	pF
Typical capacitance value tolerance		±0.3	PF
Maximum clamping voltage measured*4	$V_{\rm C}$	250	V

Reference Data

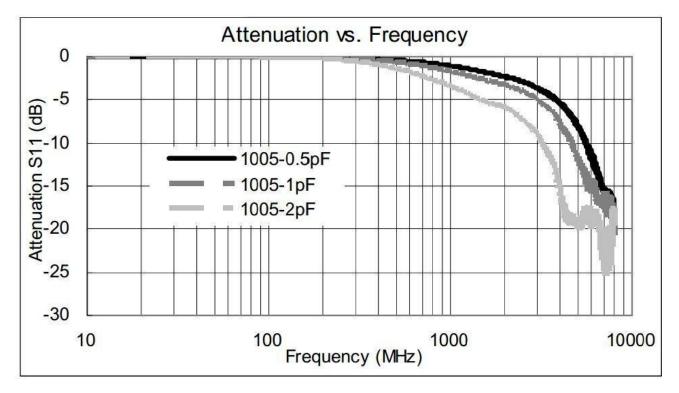
Tererence Bata			
Response time	T rise	<1	ns
Leakage current at V _B ×80%(At initial state)	I_{LVB}	<20	μΑ
Leakage current at V _B ×80%(After reliability Test)	I_{LVBA}	<100	μΑ
Operating ambient temperature		_	$^{\circ}$
		55~+125	
Storage temperature		_	${\mathbb C}$
		40~+125	
Reflow temperature profile(Recommend)		260	$^{\circ}$

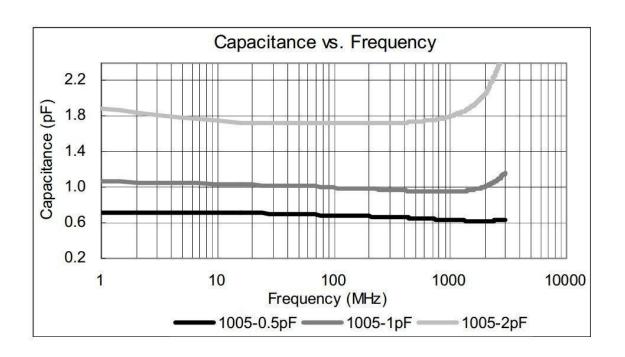




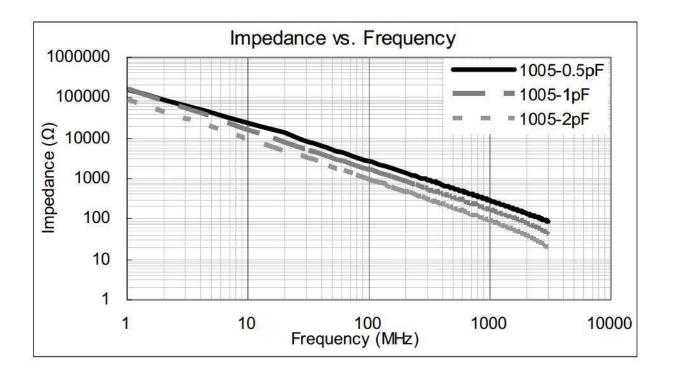




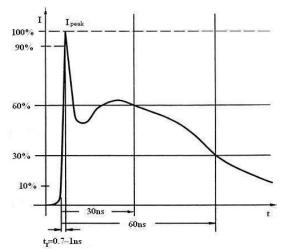








Esd Wave Form



IEC61000-4-2 Standards

SEVERITY LEVEL	AIRDIRCHARGE	DIRECT ISCHARGE
1	2 kV	2 kV
2	4 kV	4 kV
3	8 kV	6 kV
4	15 kV	8 kV

IEC61000-4-2 Compliant ESD Current Pulse Waveform



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